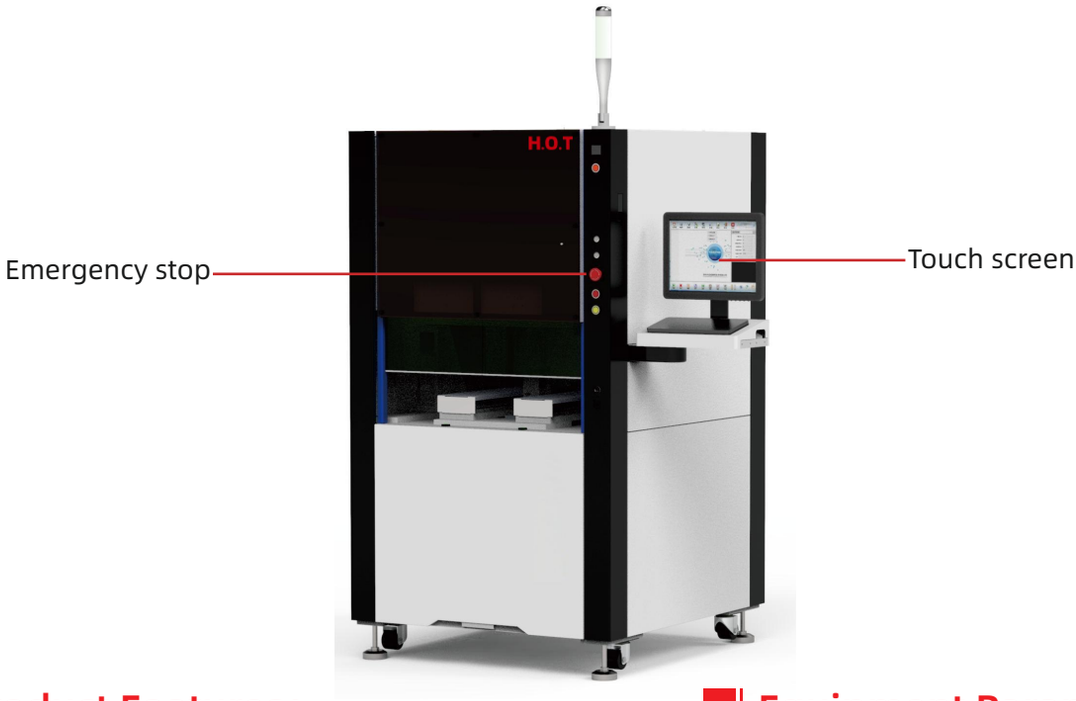
HT-LAB730
Laser Solder Ball Soldering Robot

H.O.T

Product Description:



Product Features:

- Ping-pong Operation.
- Pattern Recognition.
- Fiducial Alignment.
- Automatic Height Measurement.
- Automatic Calibration.
- Fluxless, no polltuin, no cleaning.
- Non-contact soldering,low thermal.
- Stencil-less, fast & high precision solder.
- Easy-to-use super intelligent visualized programming for soldering.

Equipment Parameters:

Model	HT-LAB730
Dimension	980*1100*1750mm
Travel Range	500*650*80/80mm
Product Max.Size	200*300mm
Motion Control Mode	IPC
Drive Mode	Servo Motor/Ball Screw
Number of Axis	6 Axes
Laser Power Range	0-300W
Travel Maximum	1000mm/s
MaxPower Consumption	185-265V/1500W
Average Power Consumption	450W
Repeat Position Accuracy	±0.01mm
Diameter of Solder Ball	0.2-1.8mm
Weight	700KG
Laser Type	Fiber Laser
Minimum Soldering Distance	0.2mm
Nitrogen Pressure	3-12Bar
Nitrogen Flow Rate	0.75L/min

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